

## N-Channel Enhancement Mode Field Effect Transistor

### Product Summary

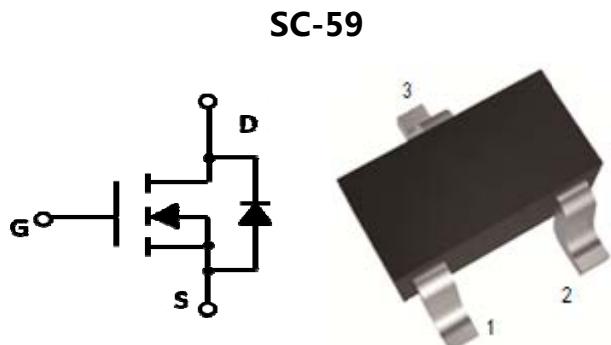
- $V_{DS}$  20V
- $I_D$  4.3A
- $R_{DS(ON)}$  (at  $V_{GS}=4.5V$ ) <27 mohm
- $R_{DS(ON)}$  (at  $V_{GS}=2.5V$ ) <37 mohm

### General Description

- Trench Power LV MOSFET technology
- High Power and current handing capability
- Marking : A2SHB

### Applications

- PWM application
- Load switch



1 : Gate 2 : Source 3 : Drain

### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	$V_{DS}$	20	V
Gate-source Voltage	$V_{GS}$	$\pm 10$	V
Drain Current  $T_A=25^\circ\text{C}$ @ Steady State	$I_D$	4.3	A
		3.5	
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	18	A
Total Power Dissipation @ $T_A=25^\circ\text{C}$	$P_D$	1.0	W
Thermal Resistance Junction-to-Ambient @ Steady State <sup>B</sup>	$R_{\theta JA}$	125	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	$^\circ\text{C}$

**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250μA	20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>C</sub> =25°C			1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±10V, V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA	0.55	0.85	1.25	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> =4.3A		21	27	mΩ
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> =3.0A		29	37	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =4.3A, V <sub>GS</sub> =0V			1.2	V
Maximum Body-Diode Continuous Current	I <sub>S</sub>				4.3	A
<b>Dynamic Parameters</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz		595		pF
Output Capacitance	C <sub>oss</sub>			106		
Reverse Transfer Capacitance	C <sub>rss</sub>			59		
<b>Switching Parameters</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =10V, I <sub>D</sub> =4.3A		6.6		nC
Gate Source Charge	Q <sub>gs</sub>			0.9		
Gate Drain Charge	Q <sub>gd</sub>			1.4		
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =4.5V, V <sub>DD</sub> =10V, R <sub>L</sub> =1.5Ω, R <sub>GEN</sub> =3Ω		13		ns
Turn-on Rise Time	t <sub>r</sub>			54		
Turn-off Delay Time	t <sub>D(off)</sub>			18		
Turn-off Fall Time	t <sub>f</sub>			11		

- A. Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.  
B. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

### Typical Performance Characteristics

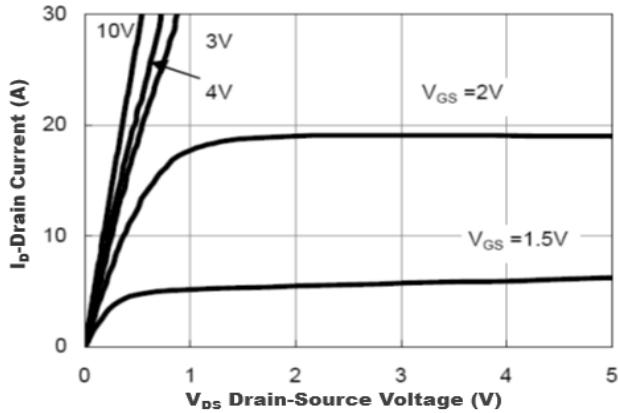


Figure1. Output Characteristics

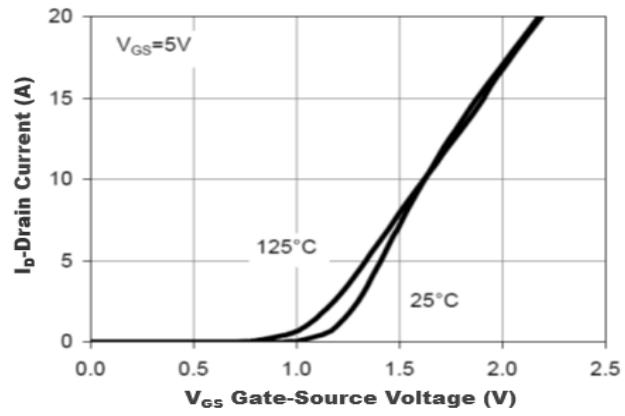


Figure2. Transfer Characteristics

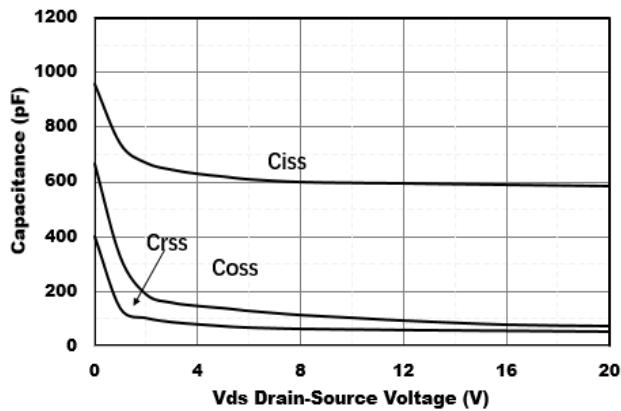


Figure3. Capacitance Characteristics

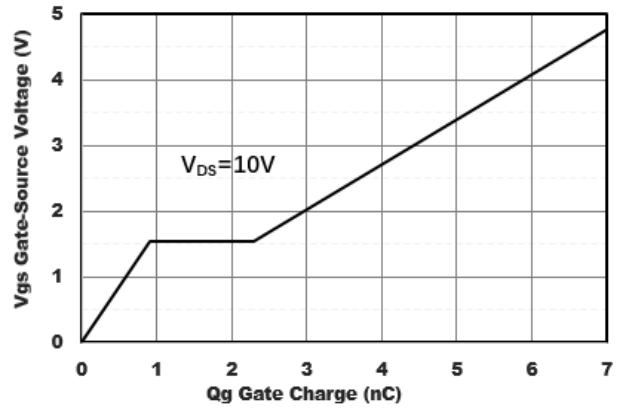


Figure4. Gate Charge

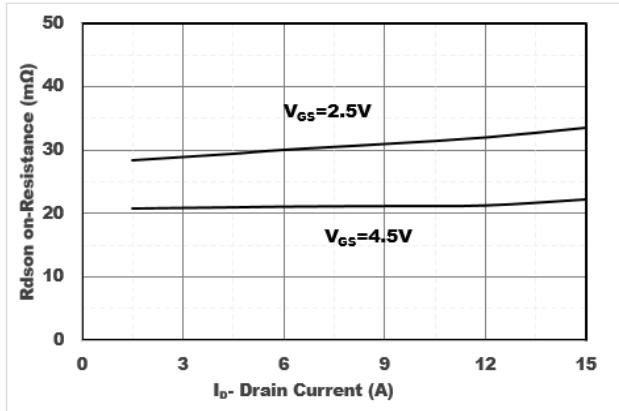


Figure5. Drain-Source on Resistance

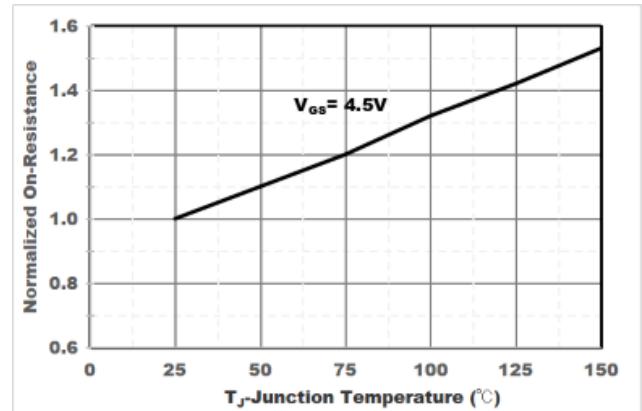


Figure6. Drain-Source on Resistance

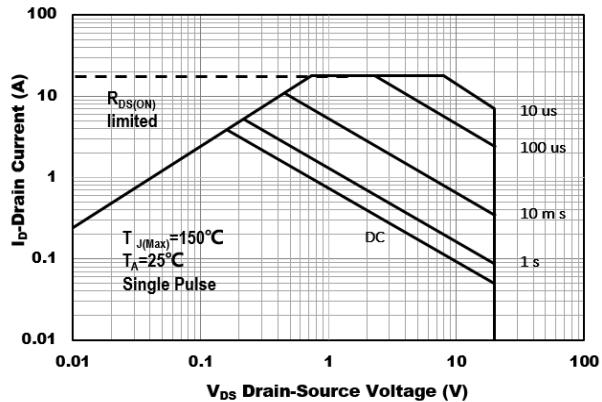


Figure7. Safe Operation Area

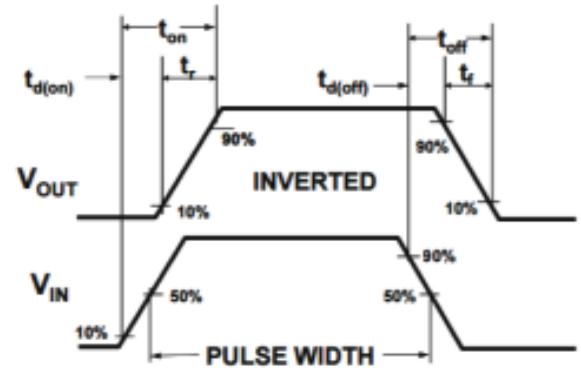


Figure8. Switching wave

**Package Outline Dimensions (UNIT: mm)**

**SC-59**

